"Gray" slots align with breaks; "white" slots are parallel with technical sessions.

Exhibitor Forum
Tuesday, May 23:

Time	Session Tue.A **Desert Vista D**	Session Tue.B **Desert Vista E**
1:30-1:50	**Wolfspeed:** Wolfspeed Update, *Chris Dimino*	
1:50-2:10	**ePAK International:** Challenges in Shipping GaAs and Special Substrate Wafers, *Nik Tryer*	
2:10-2:30	**II-VI Advanced Materials:** SiC Substrate Market Demand Growth and Manufacturing Expansion Efforts at II-VI, *Andy Souzis*	
2:30-2:45	**Microtronic:** Extend the life of your fab with a novel approach to macro defect management and excursion control, *Errol Akomer*	**Lehighton Electronics:** Eddy Current & Contactless Hall measurements in one combined system, *Danh Nguyen*
2:45-3:00	**Nanotronics:** Leveraging Computer Vision, Machine Learning, & Artificial Intelligence to Assign Causality of Defects, *Julie Orlando*	**NuFlare Technology:** NuFlare MOCVD/Epi Update, *Itaru Fujiki*
3:00-3:20	**DISCO Hi-Tec:** Disco's Technology for Compound Semiconductor Materials, *Chris Mihai*	
3:20-3:40	**EpiGaN:** From Hype to reality: GaN/Si – Where Are We Today? *Markus Behet*	
3:40-4:00	**Revasum:** Cost Effective SiC Wafer Processing, *Sarah Okada*	
4:00-4:20	**SPTS Technologies:** Dry etching of AlN & AlScN piezoelectric films for bulk acoustic wave & related devices, *Dave Thomas*	**Canon USA:** Canon Industrial Products Technology for Compound Semiconductor Applications, *Doug Shelton*
4:20-4:40	**Evatec AG:** Single compound target sputtering of $Al_{(1-x)}Sc_{(x)}N$ films for high volume manufacturing on 200mm Si wafers, *Dr. Reinhard Benz*	**FRT of America:** FRT Hybrid Metrology, *Gary Williams*
4:40-5:00	**Materion:** Development of High-Scandium Al-Sc Sputter Targets, *Vitally Myasnikov, Matthew Komertz, and David van Heerden*	**ClassOne Technology:** Reduce Gold Usage, *Kevin Witt*
5:00-5:20	**BISTel America:** Fault Detection without Modeling, *Joe Lee*	

Wednesday, May 24:

Time	Session Wed.A **Desert Vista D**	Session Wed.B **Desert Vista E**
8:00-8:20		
8:20-8:40	**Balazs NanoAnalysis:** Advanced Depth Profiling Techniques, *Victor Chia*	
8:40-9:00	**Proton OnSite:** OnSite Production of UHP Grade Hydrogen for Semiconductor and Epitaxy Applications, *David Wolff*	
9:00-9:20	**SUMIKA:** Compound Semiconductor Activities within Sumitomo Chemical, *Ken Campman*	
9:20-9:40	**Siconnex Customized Solutions:** Siconnex BATCHSPRAY Technology for Etching, Cleaning and Resist Strip, *Fabio Woerndl*	
9:40-9:55	**Oxford Instruments:** Deposition of ALD films for the use in Power Semiconductors, *Robert Gunn*	**ASAP Co.:** Single Treatment Automatic Liftoff system, *Greg Mills*
9:55-10:15	**Matheson:** Matheson Company Overview: MOCVD, Special gases, Filtration, and abatement presentation & raffle, *Jeff Blouse, Lori Sanford, Junko Lindberg*	**Center for Device Thermography and Reliability, University of Bristol:** A contactless, noninvasive technique for mapping thermal properties of heteroepitaxial wafers, *Roland Simon*
10:15-10:35	**Plasma-Therm:** Plasma-based processing solutions for sensitive devices, *Thierry Lazerand*	
10:35-10:55	**Nanometrics:** Study of Deep Ultra Violet Optical Property of AlGaN/GaN 2DEG Heterostructures, *Torsten Stoll*	
10:55-11:15	**Pozetta:** Efficient Reticle and Wafer Processing, Storage and Transport, *Artemis Vasiliades*	
11:15-11:35	**KLA-Tencor:** Candela Defect Inspection Strategy for Compound Semiconductor and Power Electronics Markets, *Anoop Somanchi*	